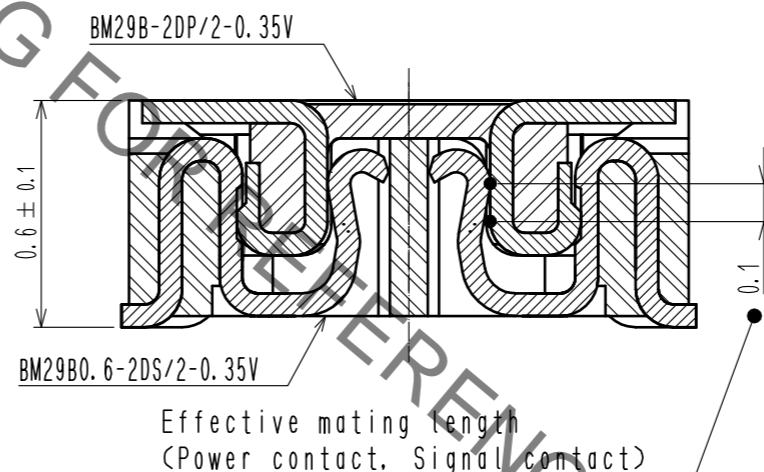
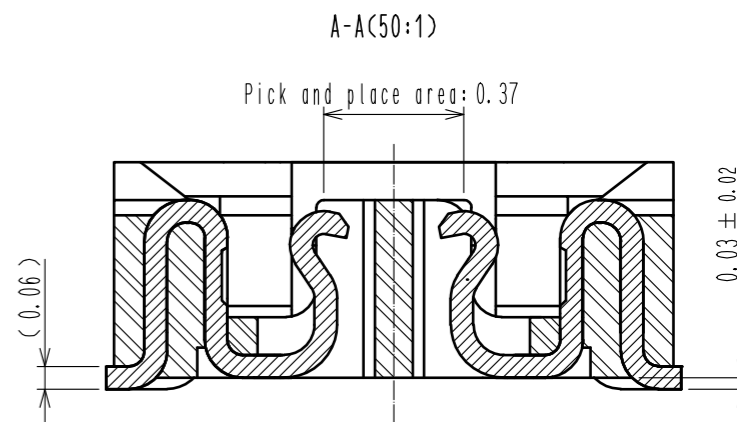
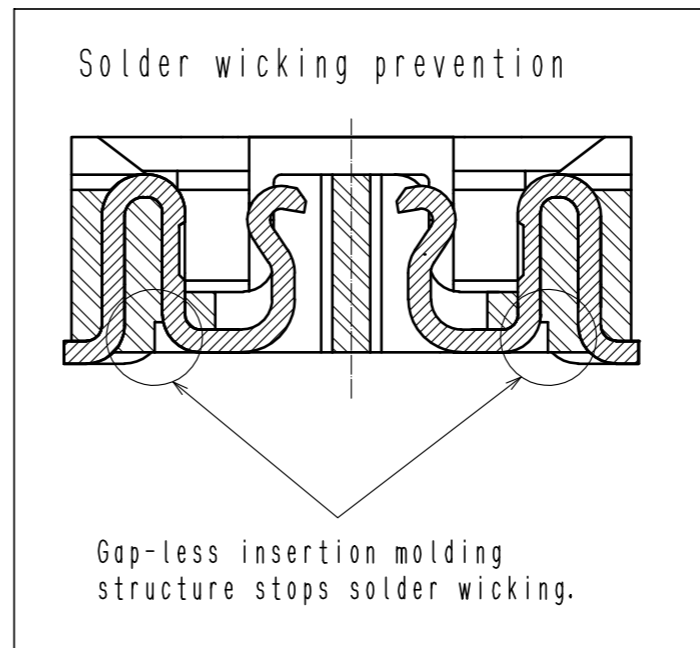
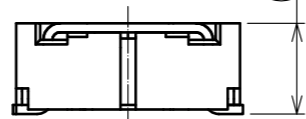
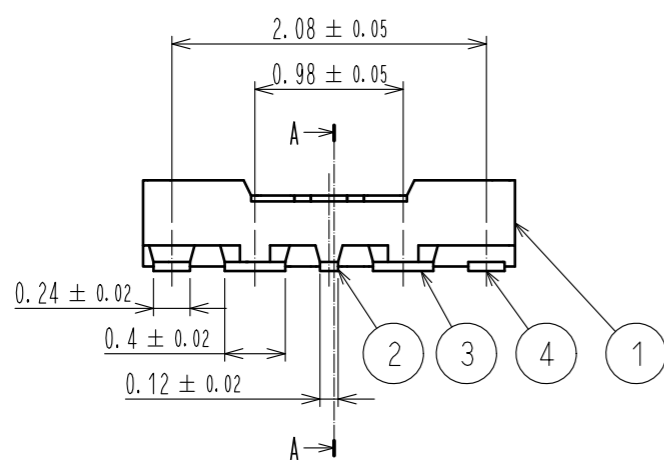
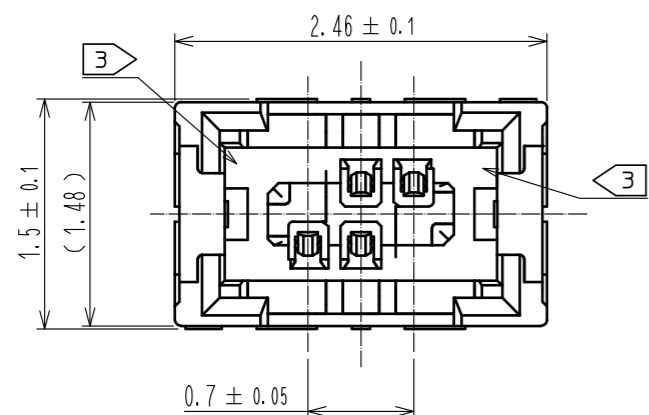


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△ Effective contact length deleted

- NOTE 1 . All lead co-planarity shall be 0.08mm MAX.
- ② . Contact plating specifications  
 Contact area : Gold 0.05μm MIN  
 SMT lead : Gold 0.05μm MIN  
 Under plating : Nickel 1μm MIN  
 (Surface : Sealing)
  - ③ . HRS mark and CAV No. are indicated in approx. position shown.

NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
4	PHOSPHOR BRONZE	②	8	PS	CLEAR. REINFORCEMENT COLLAR
3	PHOSPHOR BRONZE	②	7	PS	BLACK. PLASTIC REEL
2	PHOSPHOR BRONZE	②	6	POLYESTER	CLEAR. COVER TAPE
1	LCP	UL94 V-0. BLACK	5	PS	SMOKE GRAY. EMBOSSED CARRIER TAPE

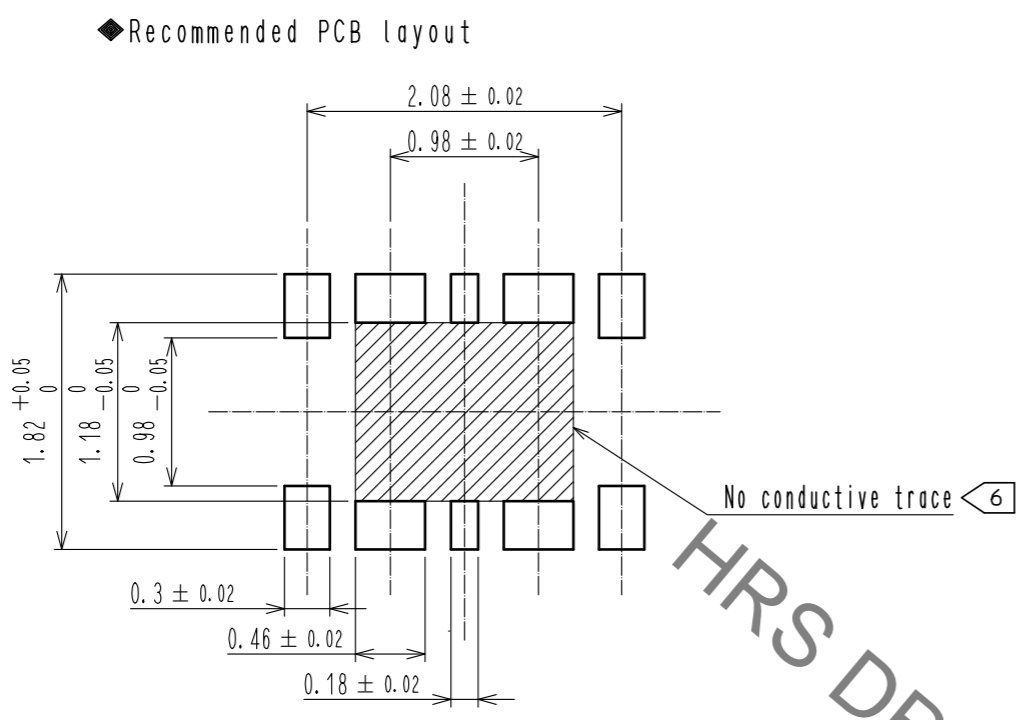
  

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	20:1	5	DIS-H-00010263	RT. OSAKI	TS. MIYAZAKI	20210727

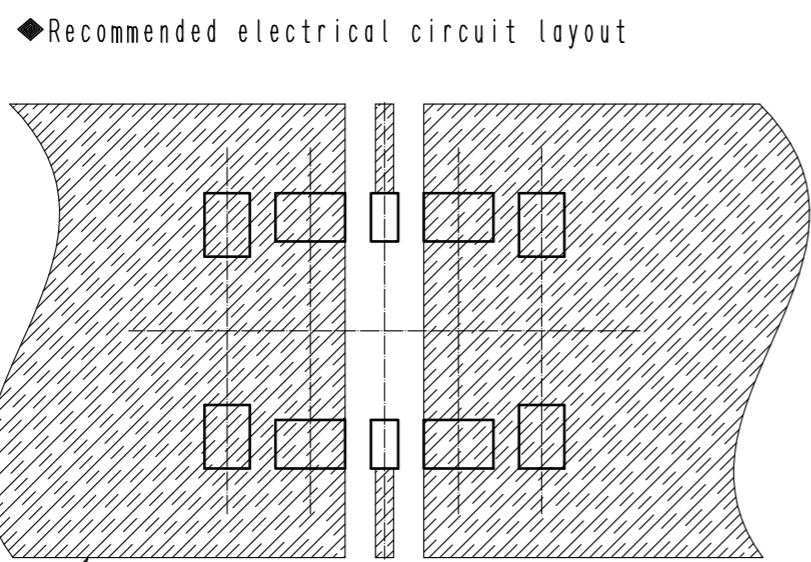
  

APPROVED	CHECKED	DESIGNED	DRAWN	DRAWING NO.	PART NO.	CODE NO.
MO. ISHIDA	WR. FUKUCHI	TY. YAMASAKI	KR. AJITO	20160106	20160106	20160106
				EDC-362699-53-01		
				BM29B0.6-2DS/2-0.35V(53)		
				CL0673-7001-0-53		①/4

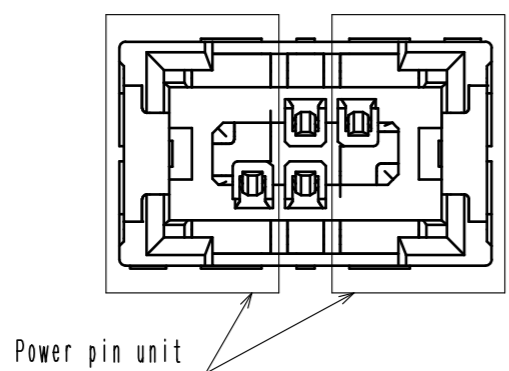
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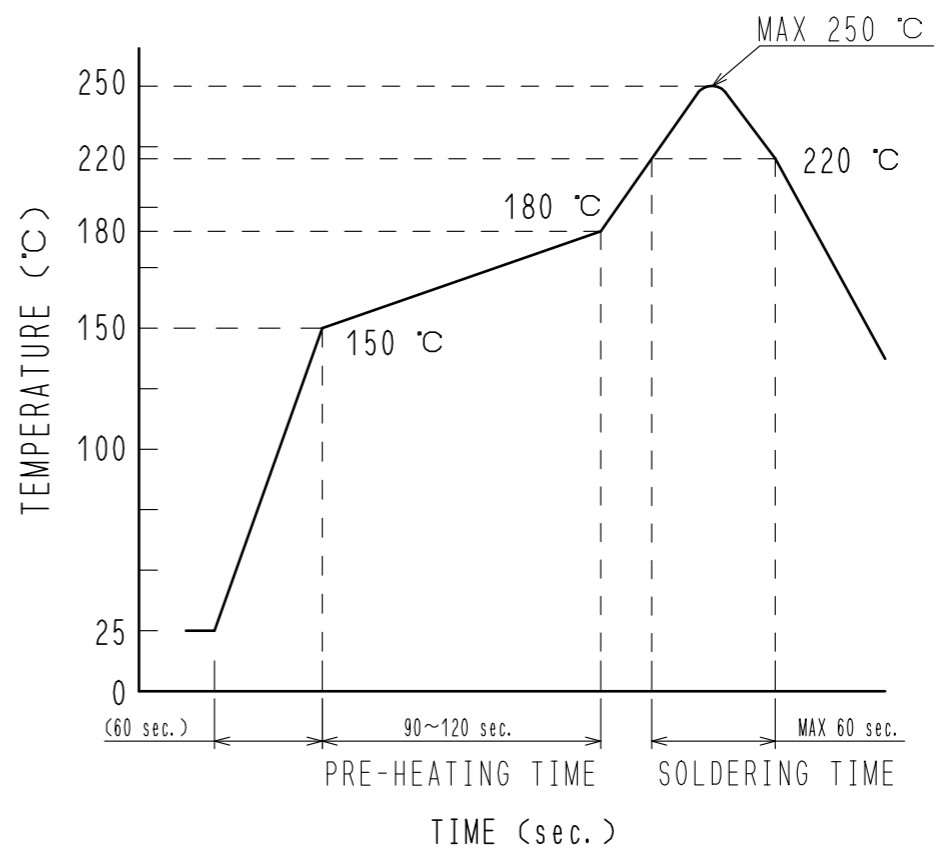
◆ Recommended metal mask dimensions  
Metal mask thickness : 80 μm 1  
(Open ratio : 100% for PCB layout)



Electrical circuit



4 Recommended reflow temperature profile using lead-free solder paste.



Reflow method: IR reflow  
Number of reflow cycles: 2 cycles MAX.  
1) Reflow time  
Duration above 220°C: 60 sec MAX.  
(Peak temperature: 250°C MAX)  
2) Pre-heat time  
Pre-heat temperature (MIN): 150°C  
Pre-heat temperature (MAX): 180°C  
Pre-heat time: 90-120 sec.

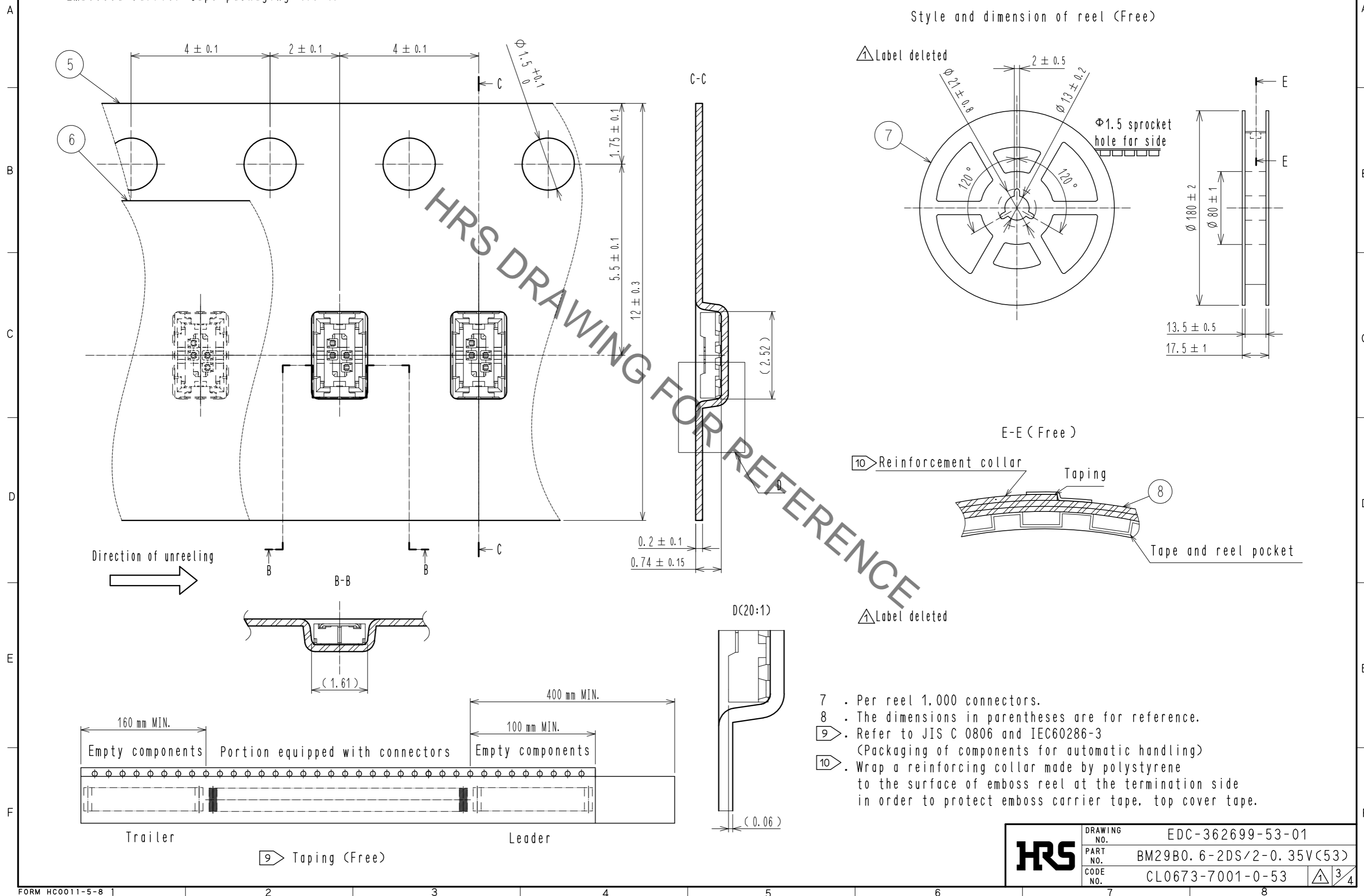
- 4 The temperatures mentioned above refer to the PCB surface temperature near the connector leads. The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.
5. Please contact us in case you will make different settings from our recommendation.
- 6 For the routing on the indicated PCB surface, apply solder resist in order for the insulation treatment.

<b>HRS</b>	DRAWING NO.	EDC-362699-53-01	
	PART NO.	BM29B0. 6-2DS/2-0.35V(53)	
	CODE NO.	CL0673-7001-0-53	<span style="border: 1px solid black; padding: 2px;">1</span> <span style="border: 1px solid black; padding: 2px;">2</span> / <span style="border: 1px solid black; padding: 2px;">4</span>

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Embossed carrier tape packaging (10:1)

Style and dimension of reel (Free)



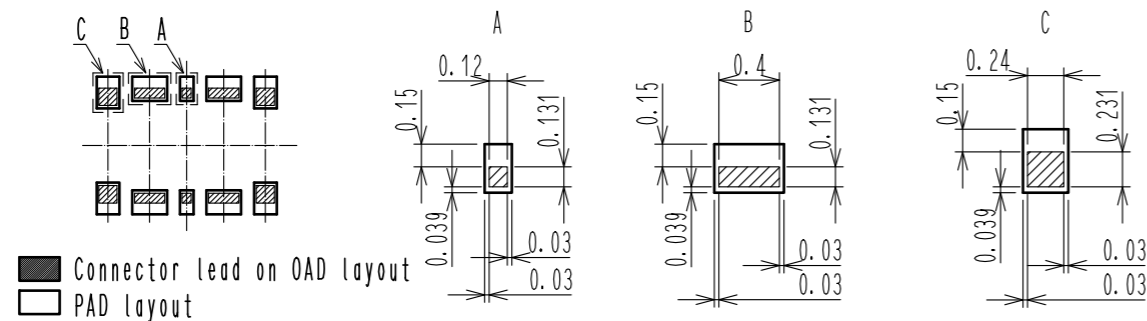
- 7 . Per reel 1,000 connectors.
- 8 . The dimensions in parentheses are for reference.
- 9 . Refer to JIS C 0806 and IEC60286-3  
(Packaging of components for automatic handling)
- 10 . Wrap a reinforcing collar made by polystyrene to the surface of emboss reel at the termination side in order to protect emboss carrier tape, top cover tape.

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	PART NO.	BM29B0. 6-2DS/2-0.35V(53)
	CODE NO.	CL0673-7001-0-53
		3/4

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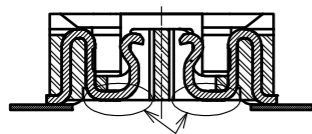
△11. PLEASE REFER TO THE PRODUCT GUIDELINE ETAD-H1016 FOR DETAIL OF CONNECTOR HANDLING.

THE POSITION BETWEEN THE CONNECTOR AND PAD



CAUTION FOR SOLDERING

THERE IS METAL EXPOSURE AREA BOTTOM OF THE CONNECTOR.  
 TO AVOID SOLDER WICKING FROM THE BOTTOM SIDE, PLEASE DESIGN PCB PAD AND STENCIL WITH RECOMMENDED DIMENSIONS.

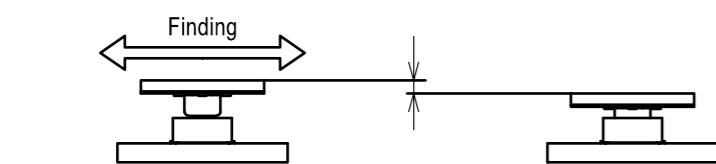
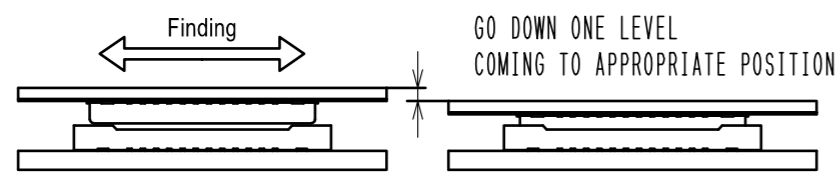


MATING METHOD

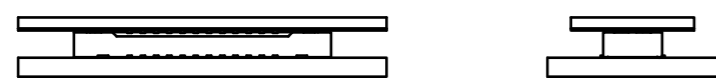
PLEASE MATE THE CONNECTOR BY HAND.

MATING PROCEDURE

- (1) FIND THE ALIGNMENT AREA TO THE CONNECTOR IN THE APPROPRIATE MATING POSITION.  
 THIS CONNECTOR HAS AN ALIGNMENT CHAMBER(GUIDANCE RIBS) ON RECEPTACLE SIDE AND 'R' ON PLUG SIDE, SO THAT THE CONNECTOR WILL BE SELF-ALIGNED.  
 WHEN THE CONNECTOR COMES TO THE APPROPRIATE POSITION, THE CONNECTOR GOES INTO THE ALIGNED POSITION.  
 WHEN ALIGNED, IT CAN BE FELT BY HAND.



- (2) WHEN GUIDING, THE CONNECTORS ARE ALIGNED PARALLEL TO EACH OTHER, WITH LONGITUDINAL AND LATERAL MOVEMENTS RESTRICTED. MATE THEM PROPERLY BY APPLYING FORCE IN THIS CONDITION.

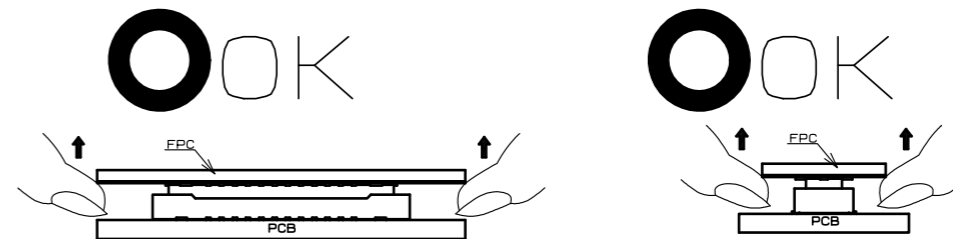


- (3) MAKE SURE THE CONNECTORS ARE MATED CORRECTLY. IF ONE SIDE IS FLOATING OR THE CONNECTORS ARE MATED IN ONE DIRECTION, UN-MATE THEM ONCE, AND THEN MATE THEM AGAIN, FOLLOWING THE PROCEDURES ABOVE FROM THE BEGINNING.

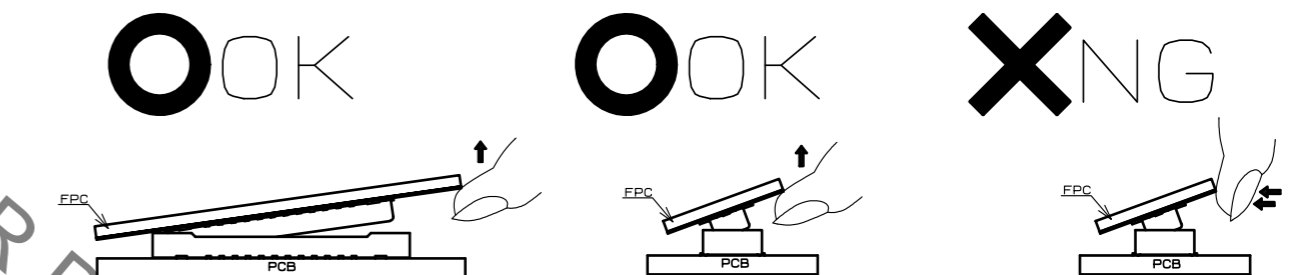
UN-MATING METHOD

PLEASE UN-MATE THE CONNECTOR BY HAND

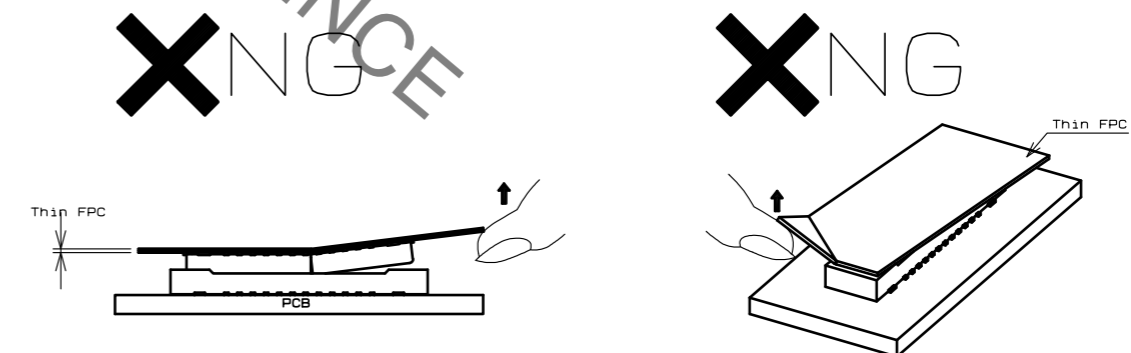
- (1) UN-MATE THE CONNECTORS PARALLEL TO EACH OTHER. HOWEVER, IF THE CONNECTORS HAVE HIGH PIN COUNTS OR THINNER FPC AND STIFFENER, IT BECOMES MORE DIFFICULT TO DO SO.



- (2) IF THE CONNECTOR CANNOT BE UN-MATED PARALLEL IT CAN BE REMOVED DIAGONALLY FROM THE PITCH DIRECTION. BE CAREFUL TO DO SO SINCE THIS ACTION APPLIES STRESS ON THE CONTACT.



- (3) IF THE FPC IS NOT RIGID, THE CONNECTOR CAN BE BROKEN. PLEASE CHECK THE ACTION OF THE FPC TO BE USED REPEATEDLY AT THE TIME OF TRIAL PRODUCTION. BE CAREFUL TO UN-MATE THEM FROM THE PITCH DIRECTION, PULLING IT FROM THE CORNER CAN ALSO RISK TO PUTTING STRESS ON CONTACTS.



<b>HRS</b>	DRAWING NO.	EDC-362699-53-01
	PART NO.	BM29B0. 6-2DS/2-0.35V(53)
	CODE NO.	CL0673-7001-0-53
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